N-Channel Enhancement-Mode Vertical DMOS FETs

Ordering Information

BV _{DSS} /	R _{DS(ON)}	V _{GS(th)}	I _{D(ON)}	Order Number / Package			
BV _{DGS}	(max)	(max)	(min)	TO-92			
350V	15Ω	1.8V	0.15A	VN3515L			
400V	<mark>12Ω</mark>	1.8V	0.15A	VN4012L			

Features

- □ Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- □ Low C_{ISS} and fast switching speeds
- Excellent thermal stability
- Integral Source-Drain diode
- High input impedance and high gain
- Complementary N- and P-channel devices

Applications

- Motor controls
- Converters
- Amplifiers

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- Telecom Switching
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

Absolute Maximum Ratings

Drain-to-Source Voltage	BV _{DSS}
Drain-to-Gate Voltage	BV _{DGS}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

Distance of 1.6 mm from case for 10 seconds.

Advanced DMOS Technology

These enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Option



Supertex Inc. does not recommend the use of its products in life support applications and will not knowingly sell its products for use in such applications unless it receives an adequate "products liability is described and limits its liability to the concerning data and advantage advantage

Thermal Characteristics

Package	I _D (continuous)*	I _D (pulsed)	Power Dissipation @ T _C = 25°C	$^{ heta_{jc}}$ °C/W	θ _{ja} °C/W	I _{DR} *	I _{DRM}
VN3515L (TO-92)	150mA	600mA	1W	125	170	150mA	600mA
VN4012L (TO-92)	160mA	650mA	1W	125	170	160mA	650mA

* I_D (continuous) is limited by max rated T_i.

Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter		Min	Тур	Max	Unit	Conditions	
	Drain-to-Source	VN3515	350			v	$V_{GS} = 0V, I_{D} = 100\mu A$	
	Breakdown Voltage	VN4012	400			, v	$G_{\rm GS} = 000$, $I_{\rm D} = 100\mu$	
V _{GS(th)}	Gate Threshold Voltage		0.6		1.8	V	$V_{GS} = V_{DS}, I_D = 1mA$	
I _{GSS}	Gate Body Leakage				10	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
I _{DSS}	Zero Gate Voltage Drain Current				1	μΑ	$V_{GS} = 0V, V_{DS} = 0.8$ Max Rating	
					100		$V_{GS} = 0V, V_{DS} = 0.8$ Max Rating $T_A = 125^{\circ}C$	
I _{D(ON)}	ON-State Drain Current		0.15	0.3		Α	$V_{DS} = 10V, V_{GS} = 4.5V$	
R _{DS(ON)} Static D	Static Drain-to-Source	100545		9.5	15	Ω	$V_{GS} = 4.5V, I_{D} = 100mA$	
		VN3515		17	35		$V_{GS} = 4.5V, I_{D} = 100mA, TA = 125^{\circ}C$	
	ON-State Resistance	VN4012		9.5	12		$V_{GS} = 4.5V, I_{D} = 100mA$	
				17	30		$V_{GS} = 4.5V, I_{D} = 100mA, TA = 125^{\circ}C$	
G _{FS}	Forward Transconductance		125	350		mប	$V_{DS} = 15V, I_{D} = 100mA$	
C _{ISS}	Input Capacitance				110			
C _{OSS}	Common Source Output Capacitance				30	pF	$V_{DS} = 25V, V_{GS} = 0V$ f = 1MHz	
C _{RSS}	Reverse Transfer Capacitance				10			
t _{d(ON)}	Turn-ON Delay Time				20			
t _r	Rise Time				20	ns	$V_{DD} = 25V$ $I_D = 100mA$ $R_{GEN} = 25\Omega$	
t _{d(OFF)}	Turn-OFF Delay Time				65			
t _f	Fall Time				65		Gen 2011	
V _{SD}	Diode Forward Voltage Drop				1.2	V	V _{GS} = 0V, I _{SD} = 160mA	

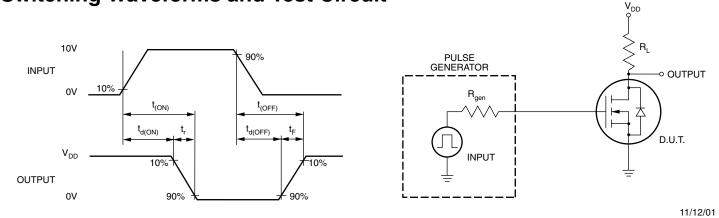
Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)

2. All A.C. parameters sample tested.

3. See TN2540 data sheet for characteristic curves.

Switching Waveforms and Test Circuit





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